

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

REDUCED MULTICUBIC DATABASE INTERPOLATION METHOD FOR OPTICAL MEASUREMENT OF DIFFRACTIVE MICROSTRUCTURES

DIFFRACTIVE MI	CROSTRUCTURES					
the specification of as Application No	July 1, 2003 (if applicable).	July 1, 2003 (if applicable).				
	t I have reviewed and underst ed by any amendment referre	and the contents of the above-identified d to above.	specification, includ	ling the		
I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR § 1.56.						
or inventor's certif	icate, or § 365(a) of any PCT tates, listed below and have a	U.S.C. § 119(a)-(d) or § 365(b) of any tender in the international application which designal is a identified below any foreign application on which priority is claimed:	ted at least one cour ion for patent or inve	ntry other		
Prior Foreign Application(s)			Priority Yes	Claimed <u>No</u>		
Number	Country	Day/Month/Year Filed				
Number	Country	Day/Month/Year Filed				
I hereby claim the	benefit under 35 U.S.C. § 11	9(3) of any United States provisional ap	plication(s) below:			
60/392,953		July 1, 2002		_		
Application Numb	er	Filing Date				
60/426,602		November 15, 2002				
Application Numb	er	Filing Date	<u> </u>			
Application Numb	er	Filing Date				

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

Application Number	Filing Date	Status: Patented, Pending, Abandoned
Application Number	Filing Date	Status: Patented, Pending, Abandoned
Application Number	Filing Date	Status: Patented, Pending, Abandoned

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Inventor's signature

| Solution | Solution